



## TG-CJ-60-60-15-PF

### Ceramic Heatsink

Version 2.130218

#### Ceramic Heatsink

T-Global's range of ceramic heatsinks have been designed from a proprietary blend of engineering ceramics to offer superior thermal management for the most demanding of applications. Compared to aluminium, ceramics confer additional benefits such as electrically isolating, resistant to corrosion, low weight and does not act like an antenna. The addition of a pre-applied thermal tape further reduces the manufacturing complexity when compared to aluminum heatsinks.

#### **Features**

Large contact area Low weight High breakdown voltage Excellent heat spreader Custom shapes possible

#### **Applications**

LED, M/B, P/S, LCD, TV, Notebook, PC, PC Telecom Device, Wireless Hub, Power transistor, Power module, CPU, Chip IC

#### **Properties**

- ✓ REACH Compliant
- ✓ ROHS Compliant

	Main Component			
Property Type	Property	Property Unit		
Physical Property	Density	g/cm³	3.66	
	Water Absorption	%	0.002	
	Sinter Temperature °C		1700	
	Acid Resistance mg,		≦0.2	
	Alkali	mg/cm³	≦0.2	
Mechanical Property	Mohs Hardness	HV	9	
	Bend Strength	nd Strength Mpa		
	Compression Intensity	Мра	≧ 620	
Thermal Property	Maximum Working Temperature	°C	1400	
	Thermal Expansion Coefficient	(1x10 <sup>-</sup> 6) mm/°C	7.8~8.3	
	Thermal Shock Resistance	T (°C)	200	
	Thermal Conductivity	W/m.k.	40~51	
Electrical Property	Resisting Rate of Volume	Ω °C	1016	
	DC Breakdown Strength	KV/mm	15.2~16.7	
	Insulation Breakdown Intensity	KV/mm	18	
	Dielectric Constant (1MHz)	(E)	10	
	Dielectric Dissipation	(tg o)	0.4*10-3	
Shelf Life	-	-	Indefinite	

#### Part Number Information

Product	Length	Width	Depth	Adhesive
TG-CJ-60-60-15-PF	60	60	15	-

<sup>\*</sup> All measurements in mm

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\* Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.

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